



DMP2035U

P-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

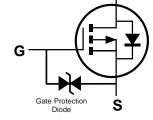
Mechanical Data

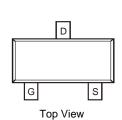
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Terminal Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)





SOT23





Top View

Internal Schematic

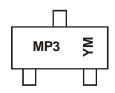
Ordering Information (Note 5 & 6)

| Part Number | Compliance | Case | Packaging |
|-------------|------------|-------|--------------------------|
| DMP2035U-7 | Standard | SOT23 | 3,000 / 7" Tape & Reel |
| DMP2035UQ-7 | Automotive | SOT23 | 3,000 / 7" Tape & Reel |
| DMP2035U-13 | Standard | SOT23 | 10,000 / 13" Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to https://www.diodes.com/quality/.
- 5. The ESD gate protection diode is only designed to protect against ESD events. No gate-source voltage greater than the maximum V_{GSS} rating (given on page 2) can be applied.
- 6. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



MP3 = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: F = 2018) M = Month (ex: 9 = September)

Date Code Key

| Year | 2009 | ~ | 2017 | 2018 | 3 201 | 19 20 |)20 | 2021 | 2022 | 2023 | 2024 | 2025 |
|-------|------|-----|------|------|-------|-------|-----|------|------|------|------|------|
| Code | W | ~ | Е | F | G | i | Н | ı | J | K | L | М |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|---|------------------|-----------------|-------|------|
| Drain-Source Voltage | V_{DSS} | -20 | V | |
| Gate-Source Voltage | V _{GSS} | ±10 | V | |
| Continuous Drain Current (Note 8) V _{GS} = -4.5V | I _D | -4.9 -4.0 | А | |
| Pulsed Drain Current (Note 9) | | I _{DM} | -24 | А |
| Maximum Continuous Body Diode Forward Curren | Is | -1.2 | A | |
| Pulsed Body Diode Forward Current (Note 9) | | Ism | -24 | Α |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|------------------|-------------|------|
| Total Power Dissipation (Note 7) | P_{D} | 0.81 | W |
| Thermal Resistance, Junction to Ambient (Note 7) | $R_{\theta JA}$ | 153.5 | °C/W |
| Total Power Dissipation (Note 8) | P_{D} | 1.2 | W |
| Thermal Resistance, Junction to Ambient (Note 8) | $R_{\theta JA}$ | 100 | °C/W |
| Operating and Storage Temperature Range | T_{J}, T_{STG} | -55 to +150 | °C |

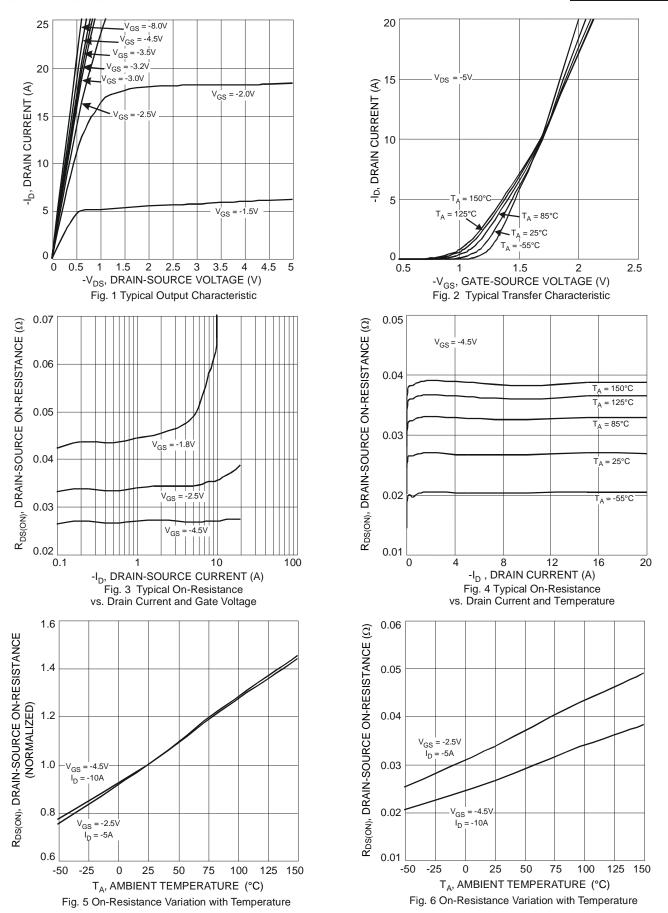
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|------|----------------|----------------|------|---|--|
| DFF CHARACTERISTICS (Note 10) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -20 | _ | 1 | ٧ | $V_{GS} = 0V, I_D = -250\mu A$ | |
| Zero Gate Voltage Drain Current T _J = +25°C | I _{DSS} | 1 | _ | -1.0 | μΑ | $V_{DS} = -20V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±10 | μΑ | $V_{GS} = \pm 8V$, $V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 10) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -0.4 | -0.7 | -1.0 | V | $V_{DS} = V_{GS}, I_D = -250 \mu A$ | |
| | | | 23 30 41 | 35 45 62 | | $V_{GS} = -4.5V, I_D = -4.0A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | | | mΩ | $V_{GS} = -2.5V, I_D = -4.0A$ | |
| | | | | | | $V_{GS} = -1.8V, I_D = -2.0A$ | |
| Forward Transfer Admittance | Y _{fs} | | 14 | 1 | s | $V_{DS} = -5V, I_{D} = -4A$ | |
| Diode Forward Voltage | V_{SD} | _ | -0.7 | -1.0 | V | $V_{GS} = 0V, I_{S} = -1A$ | |
| DYNAMIC CHARACTERISTICS (Note 11) | | | | | | | |
| Input Capacitance | C _{iss} | - | 1,610 | - | pF | V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz | |
| Output Capacitance | Coss | 1 | 157 | 1 | pF | | |
| Reverse Transfer Capacitance | C _{rss} | | 145 | 1 | pF | 1 - 1.01/11/2 | |
| Gate Resistance | R_g | _ | 9.45 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge | Q_g | _ | 15.4 | _ | nC | | |
| Gate-Source Charge | Q_{gs} | _ | 2.5 | _ | nC | $V_{GS} = -4.5V, V_{DS} = -10V,$ $I_{D} = -4A$ | |
| Gate-Drain Charge | Q_{gd} | _ | 3.3 | _ | nC | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 16.8 | _ | ns | | |
| Turn-On Rise Time | t _R | _ | 12.4 | _ | ns | $V_{DS} = -10V, V_{GS} = -4.5V,$ $R_{L} = 10\Omega, R_{g} = 6.0\Omega, I_{D} = -1A$ | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 94.1 | _ | ns | | |
| Turn-Off Fall Time | t _F | | 42.4 | | ns | | |

Notes:

- 7. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 8. Device mounted on FR-4 substrate PC board, 2oz copper, with 25mm X 25mm square copper plate.
- 9. Repetitive rating, pulse width limited by junction temperature.
- 10. Short duration pulse test used to minimize self-heating effect.
- 11. Guaranteed by design. Not subject to product testing.







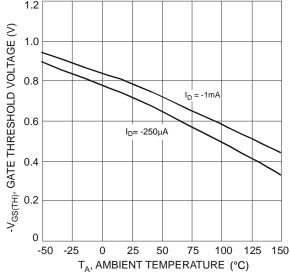
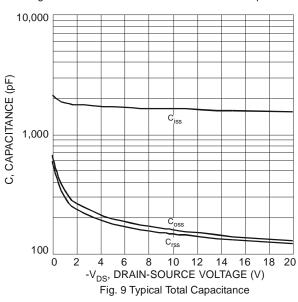
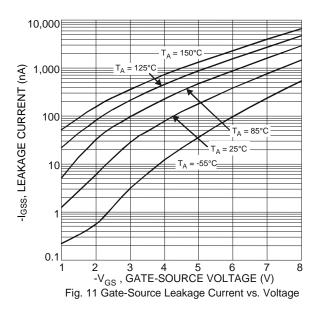
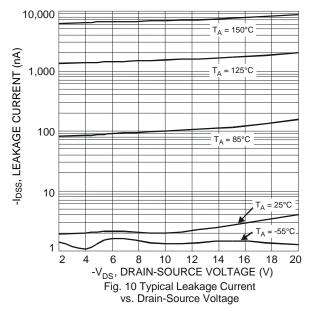
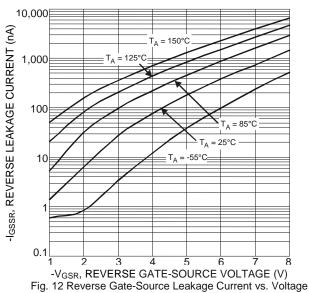


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

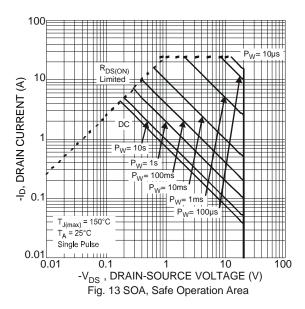












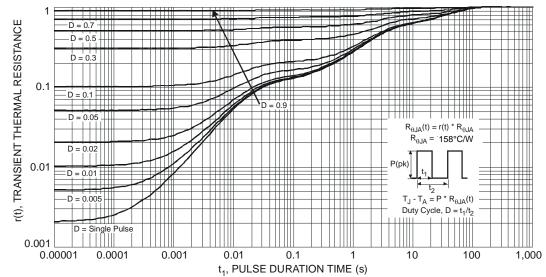


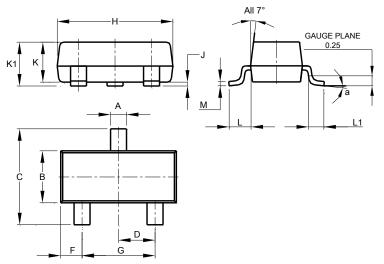
Fig. 14 Transient Thermal Response



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

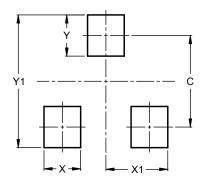


| SOT23 | | | | | | | |
|----------------------|-------|-------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.37 | 0.51 | 0.40 | | | | |
| В | 1.20 | 1.40 | 1.30 | | | | |
| C | 2.30 | 2.50 | 2.40 | | | | |
| D | 0.89 | 1.03 | 0.915 | | | | |
| F | 0.45 | 0.60 | 0.535 | | | | |
| G | 1.78 | 2.05 | 1.83 | | | | |
| Н | 2.80 | 3.00 | 2.90 | | | | |
| J | 0.013 | 0.10 | 0.05 | | | | |
| K | 0.890 | 1.00 | 0.975 | | | | |
| K1 | 0.903 | 1.10 | 1.025 | | | | |
| L | 0.45 | 0.61 | 0.55 | | | | |
| L1 | 0.25 | 0.55 | 0.40 | | | | |
| М | 0.085 | 0.150 | 0.110 | | | | |
| а | 0° | 8° | | | | | |
| All Dimensions in mm | | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 2.0 |
| Х | 0.8 |
| X1 | 1.35 |
| Υ | 0.9 |
| V1 | 2.0 |



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